

### **General Description**

The MAX9158 is a guad bus LVDS (BLVDS) transceiver for heavily loaded, half-duplex multipoint buses. A 44lead QFN package and flow-through pinout allow the transceiver to be placed near the connector. The MAX9158 drives LVDS levels into a  $27\Omega$  load (double terminated, heavily loaded LVDS bus) at up to 200Mbps. An input fail-safe circuit ensures the receiver output is high when the differential inputs are open, or undriven and shorted, or undriven and terminated. The MAX9158 operates from a single 3.3V supply, consuming 77mA supply current with drivers enabled, and 19.9mA with drivers disabled.

The MAX9158's high-impedance I/Os (except for receiver outputs) when VCC = 0V or open, combined with glitchfree power-up and power-down, allow hot swapping of cards in multicard bus systems; 7.3pF (max) BLVDS I/O capacitance minimizes bus loading.

The MAX9158 is offered in a 7mm × 7mm 44-lead QFN package, and is fully specified for the -40°C to +85°C extended temperature range. Refer to the MAX9157 data sheet for a quad BLVDS transceiver with hysteresis in 32lead QFN and TQFP packages. Refer to the MAX9129 data sheet for a guad BLVDS driver, ideal for dual multipoint full-duplex buses.

### **Applications**

Add/Drop Muxes Cellular Phone Base

Stations Digital Cross-Connects **DSLAMs** Network

Switches/Routers Multipoint Buses

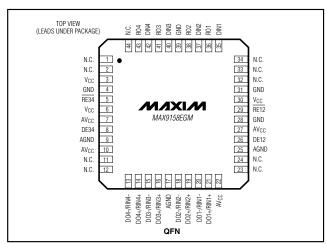
### Features

- ♦ 44-Lead QFN Package
- ♦ 1ns (min) Driver Transition Time (0% to 100%) **Minimizes Reflections**
- ♦ Guaranteed 7.3pF (max) Bus Load Capacitance
- ♦ Glitch-Free Power-Up and Power-Down
- ♦ Hot-Swappable, High-Impedance I/O with V<sub>CC</sub> = **0V or Open**
- ♦ Guaranteed 200Mbps Driver Data Rate
- ♦ Low-Jitter Fail-Safe Circuit
- **♦ Flow-Through Pinout**

### **Ordering Information**

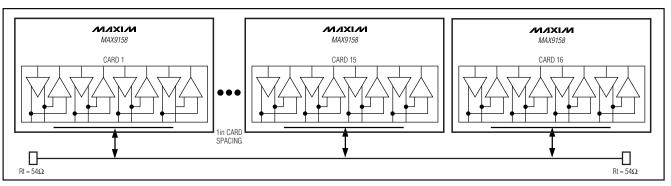
PART	TEMP RANGE	PIN-PACKAGE
MAX9158EGM	-40°C to +85°C	44 QFN (7mm × 7mm)

### **Pin Configuration**



Functional Diagram appears at end of data sheet.

### Typical Operating Circuit



MIXIM

Maxim Integrated Products 1

#### **ABSOLUTE MAXIMUM RATINGS**

V <sub>CC</sub> , AV <sub>CC</sub> to GND	0.3V to +4.0V
DO_+/RIN_+, DO/RIN to GND.	0.3V to +4.0V
DIN_, DE_, RE_ to GND	0.3V to +4.0V
RO_ to GND	0.3V to (V <sub>CC</sub> + 0.3V)
AGND to GND	0.3V to +0.3V
Short-Circuit Duration (DO_+/RIN_+	+, DO/RIN)Continuous
Continuous Power Dissipation (TA =	= +70°C)
44-Lead QFN (derate 24.3mW/°C	C above +70°C)2105mW

nperature Range	65°C to +150°C
unction Temperature	+150°C
emperature Range	40°C to +85°C
ion	
	DO/RIN)±4kV
erature (soldering, 10s)	+300°C
	unction Temperatureemperature Rangeion ody Model (DO_+/RIN_+,

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### DC ELECTRICAL CHARACTERISTICS

 $(V_{CC}=3.0V\ to\ 3.6V,\ R_L=27\Omega\ \pm1\%,\ receiver\ differential\ input\ voltage\ |V_{ID}|=0.1V\ to\ 3.0V,\ receiver\ input\ common-mode\ voltage\ V_{CM}=0.05V\ to\ 2.4V,\ receiver\ input\ voltage\ range=0V\ to\ 3.0V,\ DE_=\ high,\ \overline{RE}_=\ low,\ T_A=-40^{\circ}C\ to\ +85^{\circ}C,\ unless\ otherwise\ noted.$  Typical values are at  $V_{CC}=3.3V,\ |V_{ID}|=0.2V,\ V_{CM}=1.2V,\ and\ T_A=+25^{\circ}C.)$  (Notes 1 and 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
BLVDS (DO_+/RIN_+, DO/RIN)							
Differential Input High Threshold	V <sub>TH</sub>	DE_ = low		4.0	100	mV	
Differential Input Low Threshold	V <sub>TL</sub>	DE_ = low	-100	-4.3		mV	
Input Current	las las	$0.1V \le  V_{ID}  \le 0.6V$ , DE_ = low	-15	±1.7	+15	5	
Input Current	I <sub>IN+</sub> , I <sub>IN-</sub>	$0.6V <  V_{ID}  \le 1.2V$ , DE_ = low	-20	±2.3	+20	μΑ	
Input Desistance	R <sub>IN1</sub>	V <sub>CC</sub> = 3.6V, 0V or open, Figure 1	53			kΩ	
Input Resistance	R <sub>IN2</sub>	V <sub>CC</sub> = 3.6V, 0V or open, Figure 1	148			K22	
Dower Off Innut Current	I <sub>INO+</sub> ,	0.1V ≤   V <sub>ID</sub>   ≤ 0.6V, V <sub>CC</sub> = 0V or open	-15	±0.9	+15		
Power-Off Input Current	I <sub>INO</sub> -	0.6V < VID ≤ 1.2V, VCC = 0V or open	-20	±1.9	+20	μΑ	
Differential Output Voltage	V <sub>OD</sub>	Figure 2	250	398	460	mV	
Change in Magnitude of VOD for Complementary Output States	ΔV <sub>OD</sub>	Figure 2		1	25	mV	
Offset Voltage	Vos	Figure 2	1.185	1.274	1.435	V	
Change in Magnitude of VOS for Complementary Output States	ΔV <sub>OS</sub>	Figure 2		1.9	25	mV	
Output High Voltage	VoH	Figure 2		1.473	1.650	V	
Output Low Voltage	V <sub>OL</sub>	Figure 2	0.950	1.075		V	
	loo	DIN_ = high, DO_+/RIN_+ = 0V or VCC, DO/RIN = 0V or VCC	-30		+30	m /\	
Output Short-Circuit Current	los	DIN_ = low, DO/RIN = 0V or VCC, DO_+/RIN_+ = 0V or VCC	-30		+30	mA	

### **DC ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{CC}=3.0V\ to\ 3.6V,\ R_L=27\Omega\ \pm1\%,\ receiver\ differential\ input\ voltage\ |V_{ID}|=0V.1V\ to\ 3.0V,\ receiver\ input\ common-mode\ voltage\ V_{CM}=0.05V\ to\ 2.4V,\ receiver\ input\ voltage\ range=0V\ to\ 3.0V,\ DE_=high,\ \overline{RE}_=low,\ T_A=-40^{\circ}C\ to\ +85^{\circ}C,\ unless\ otherwise\ noted.$  Typical values are at  $V_{CC}=3.3V,\ |V_{ID}|=0.2V,\ V_{CM}=1.2V,\ and\ T_A=+25^{\circ}C.)$  (Notes 1 and 2)

PARAMETER	SYMBOL		CONDITIONS	MIN	TYP	MAX	UNITS
Differential Output Short-Circuit Current Magnitude (Note 3)	Iosd	DIN_ = high or l	ow, V <sub>OD</sub> = 0V		14.8	30	mA
Capacitance at Bus Pins (Note 3)	Соитрит		m DO_+/RIN_+ or $R$ SND, $R$ VCC = 3.6V or 0V			7.3	pF
LVCMOS/LVTTL OUTPUTS (RO_	)						
Output High Voltage	Voн	I <sub>OH</sub> = -4.0mA, DE_ = low	Open, undriven short, or undriven $27\Omega$ parallel termination	V <sub>CC</sub> - 0.3	V <sub>CC</sub> - 0.138		V
		·	VID = 100mV	V <sub>CC</sub> - 0.3	V <sub>CC</sub> - 0.138		
Output Low Voltage	V <sub>OL</sub>	$I_{OL} = 4.0 \text{mA}, V_{II}$	$D = -100 \text{mV}, DE_{-} = \text{low}$		0.176	0.25	V
Dynamia Output Current	lon	VID = 100mV, V	RO_ = VCC - 1.0V, DE_ = low	-15	-25.8	-40	A
Dynamic Output Current	IOD	VID = -100mV, \	$V_{RO}$ = 1.0V, DE_ = low	12	20.7	40	mA
Output Short-Circuit Current (Note 4)	los	V <sub>ID</sub> = 100mV, V <sub>RO</sub> _ = 0V, DE_ = low			-45	-130	mA
Output High-Impedance Current	loz	$\overline{RE}$ = high, $V_{RC}$	) = 0V or VCC	-10	0.1	+10	μΑ
Capacitance at Receiver Output (Note 3)	Соитрит	Capacitance from RO_ to GND, VCC = 3.6V or 0V				4.6	pF
LVCMOS/LVTTL INPUTS (DIN, D	E, RE)			•			
Input High Voltage	VIH			2.0		Vcc	V
Input Low Voltage	VIL			GND		0.8	V
Input Current	liN	$V_{DE_{-}}, V_{\overline{RE_{-}}}, V_{DIN_{-}} = high or low$		-20		+20	μΑ
Power-Off Input Current	lino	V <sub>DE</sub> , V <sub>RE</sub> , V <sub>DIN</sub> = 3.6V or 0V, V <sub>CC</sub> = 0V or open		-20		+20	μΑ
SUPPLY							
Supply Current Drivers and Receivers Enabled	Icc	DE_ = high, RE_	_ = low, R <sub>L</sub> = 27Ω		77	95	mA
Supply Current Drivers Enabled and Receivers Disabled	ICCD	DE_ = high, RE_	= high, $R_L = 27\Omega$		77	95	mA
Supply Current Drivers Disabled and Receivers Enabled	ICCR	DE_ = low, RE_ = low			19.9	30	mA
Supply Current Drivers Disabled and Receivers Disabled	ICCZ	DE_ = low, RE_	= high		19.9	30	mA

#### **AC ELECTRICAL CHARACTERISTICS**

 $(V_{CC}=3.0 \text{V to } 3.6 \text{V}, R_L=27\Omega \pm 1 \%$ , receiver differential input voltage  $|V_{ID}|=0.15 \text{V to } V_{CC}$ , receiver input voltage range = 0V to  $V_{CC}$ , input frequency to differential inputs = 100MHz, input frequency to LVCMOS/LVTTL inputs = 100MHz, LVCMOS/LVTTL inputs = 0V to  $V_{CC}$  with 2ns (10% to 90%) transition times. Differential input voltage transition time = 1ns (20% to 80%). Receiver input common-mode voltage  $V_{CM}=0.075 \text{V}$  to 2.4V,  $D_{CM}=1.2 \text{V}$ ,  $V_{CM}=1.2 \text{V}$ , and  $V_{CM}=1.2 \text{V}$ ,

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
DRIVER						
Differential Propagation Delay High to Low	tPHLD	RE_ = high, C <sub>L</sub> = 10pF, Figures 3, 4	1.2	1.96	2.5	ns
Differential Propagation Delay Low to High	tPLHD	RE_ = high, C <sub>L</sub> = 10pF, Figures 3, 4	1.1	1.87	2.4	ns
Differential Skew   tpHLD - tpLHD   (Note 6)	tSKD1	RE_ = high, C <sub>L</sub> = 10pF, Figures 3, 4		91	250	ps
Channel-to-Channel Skew (Note 7)	tccsk	RE_ = high, C <sub>L</sub> = 10pF, Figures 3, 4		119	350	ps
Chip-to-Chip Skew (Note 8)	tskD2	RE_ = high, C <sub>L</sub> = 10pF, Figures 3, 4		0.45	0.90	ns
Chip-to-Chip Skew (Note 9)	T <sub>SKD3</sub>	RE_ = high, C <sub>L</sub> = 10pF, Figures 3, 4			1.4	ns
Rise Time	tTLH	RE_ = high, C <sub>L</sub> = 10pF, Figures 3, 4	0.6	1.07	1.4	ns
Fall Time	tTHL	RE_ = high, C <sub>L</sub> = 10pF, Figures 3, 4	0.6	1.10	1.4	ns
Disable Time High to Z	tphz	RE_ = high, C <sub>L</sub> = 10pF, Figures 5, 6		2.8	5	ns
Disable Time Low to Z	tpLZ	RE_ = high, C <sub>L</sub> = 10pF, Figures 5, 6		2.8	5	ns
Enable Time Z to High	tpzh	RE_ = high, C <sub>L</sub> = 10pF, Figures 5, 6		4.6	6	ns
Enable Time Z to Low	tpzL	RE_ = high, C <sub>L</sub> = 10pF, Figures 5, 6		4.5	6	ns
Maximum Operating Frequency (Note 10)	fMAX	RE_ = high, C <sub>L</sub> = 10pF, Figures 5, 6	100			MHz
RECEIVER						
Differential Propagation Delay High to Low	tPHLD	DE_ = low, Figures 7, 8; C <sub>L</sub> = 15pF	1.5	2.21	3.5	ns
Differential Propagation Delay Low to High	tPLHD	DE_ = low, Figures 7, 8; C <sub>L</sub> = 15pF	1.5	2.13	3.5	ns
Differential Skew   tPHLD - tPLHD   (Note 6)	tskD1	DE_ = low, Figures 7, 8; C <sub>L</sub> = 15pF		74	250	ps
Channel-to-Channel Skew (Note 7)	tccsk	DE_ = low, Figures 7, 8; C <sub>L</sub> = 15pF		96	350	ps
Chip-to-Chip Skew (Note 8)	tskd2	DE_ = low, Figures 7, 8; C <sub>L</sub> = 15pF		0.63	1.6	ns
Chip-to-Chip Skew (Note 9)	tskd3	DE_ = low, Figures 7, 8; C <sub>L</sub> = 15pF			2.0	ns
Rise Time	tTLH	DE_ = low, Figures 7, 8; C <sub>L</sub> = 15pF	0.5	1.09	1.6	ns

### **AC ELECTRICAL CHARACTERISTICS (continued)**

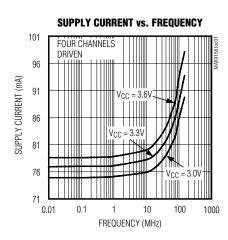
 $(V_{CC}=3.0 \text{V to } 3.6 \text{V}, R_L=27\Omega\pm1\%$ , receiver differential input voltage  $|V_{ID}|=0.15 \text{V to } V_{CC}$ , receiver input voltage range = 0V to  $V_{CC}$ , input frequency to differential inputs = 100MHz, input frequency to LVCMOS/LVTTL inputs = 100MHz, LVCMOS/LVTTL inputs = 0V to  $V_{CC}$  with 2ns (10% to 90%) transition times. Differential input voltage transition time = 1ns (20% to 80%). Receiver input common-mode voltage  $V_{CM}=0.075 \text{V}$  to 2.4V,  $D_{CM}=1.0 \text{V}$ ,  $V_{CM}=1.2 \text{V}$ , and  $V_{CM}=1.2 \text{V}$ , and

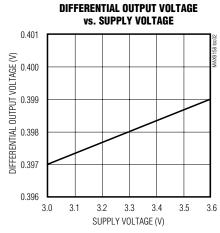
PARAMETER	SYMBOL	CONDITIONS		TYP	MAX	UNITS
Fall Time	t <sub>THL</sub>	DE_ = low, Figures 7, 8, C <sub>L</sub> = 15pF	0.7	1.24	1.8	ns
Disable Time High to Z	t <sub>PHZ</sub>	DE_ = low, R <sub>L</sub> = $500\Omega$ , C <sub>L</sub> = $15$ pF, Figures 9, 10		6.0	8	ns
Disable Time Low to Z	tpLZ	DE_ = low, R <sub>L</sub> = $500\Omega$ , C <sub>L</sub> = $15$ pF, Figures 9, 10		6.5	8	ns
Enable Time Z to High	tpzh	DE_ = low, R <sub>L</sub> = $500\Omega$ , C <sub>L</sub> = $15$ pF, Figures 9, 10		4.3	7	ns
Enable Time Z to Low	tpZL	DE_ = low, R <sub>L</sub> = $500\Omega$ , C <sub>L</sub> = $15$ pF, Figures 9, 10		4.3	7	ns
Maximum Operating Frequency (Note 10)	f <sub>MAX</sub>	DE_ = low, C <sub>L</sub> = 15pF	100			MHz

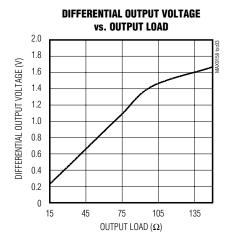
- **Note 1:** Current into a pin is defined as positive. Current out of a pin is defined as negative. All voltages are referenced to ground except V<sub>TH</sub>, V<sub>TL</sub>, V<sub>ID</sub>, V<sub>OD</sub>, and ΔV<sub>OD</sub>.
- **Note 2:** Maximum and minimum limits over temperature are guaranteed by design and characterization. Devices are production tested at  $T_A = +25$ °C.
- **Note 3:** Guaranteed by design and characterization.
- Note 4: Short only one output at a time. Do not exceed the absolute maximum junction temperature specification.
- Note 5: CL includes scope probe and test fixture capacitance.
- Note 6: t<sub>SKD1</sub> is the magnitude difference of differential propagation delays in a channel. t<sub>SKD1</sub> = I t<sub>PHLD</sub> t<sub>PLHD</sub> I.
- Note 7: t<sub>CCSK</sub> is the magnitude difference of the t<sub>PLHD</sub> or t<sub>PHLD</sub> of one channel and the t<sub>PLHD</sub> or t<sub>PHLD</sub> of any other channel on the same part.
- **Note 8:** t<sub>SKD2</sub> is the magnitude difference of any differential propagation delays between parts operating over rated conditions at the same V<sub>CC</sub> and within 5°C of each other.
- Note 9: t<sub>SKD3</sub> is the magnitude difference of any differential propagation delays between parts operating over rated conditions.
- Note 10: Meets data sheet specifications while operating at minimum f<sub>MAX</sub> rating.

### Typical Operating Characteristics

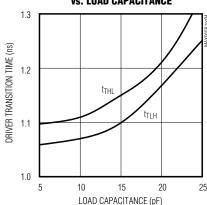
 $(V_{CC} = 3.3V, R_L = 27\Omega, driver C_L = 10pF, receiver C_L = 15pF, IV_{IDI} = 200mV, V_{CM} = 1.2V, f_{IN} = 20MHz, T_A = +25^{\circ}C, unless otherwise noted.)$ 



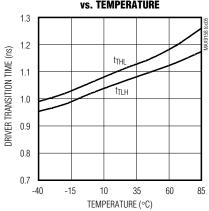




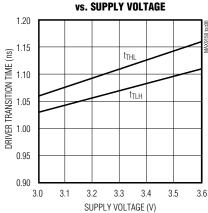
# DRIVER TRANSITION TIME vs. LOAD CAPACITANCE



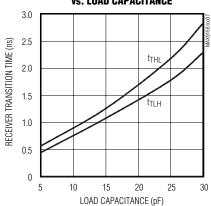




# DRIVER TRANSITION TIME



# RECEIVER TRANSITION TIME vs. LOAD CAPACITANCE



### \_\_\_\_\_Pin Description

		-
PIN	NAME	FUNCTION
1, 2, 11, 12, 23, 24, 32, 33, 34, 44	N.C.	No Connection. Not internally connected.
3, 6, 30	VCC	Digital Power Supply
4, 28, 31, 39	GND	Digital Ground
5	RE34	Receiver Channels 3 and 4 Enable (Enable Low). Drive RE34 low to enable receiver channels 3 and 4. Internal pullup to V <sub>CC</sub> .
7, 10, 22, 27	AVCC	Analog Power Supply. Connect to board VCC.
8	DE34	Driver Channels 3 and 4 Enable (Enable High). Drive DE34 high to enable driver channels 3 and 4. Internal pullup to $V_{\rm CC}$ .
9, 17, 25	AGND	Analog Ground. Connect to board ground.
13	DO4-/RIN4-	Channel 4 Inverting BLVDS Input/Output
14	DO4+/RIN4+	Channel 4 Noninverting BLVDS Input/Output
15	DO3-/RIN3-	Channel 3 Inverting BLVDS Input/Output
16	DO3+/RIN3+	Channel 3 Noninverting BLVDS Input/Output
18	DO2-/RIN2-	Channel 2 Inverting BLVDS Input/Output
19	DO2+/RIN2+	Channel 2 Noninverting BLVDS Input/Output
20	DO1-/RIN1-	Channel 1 Inverting BLVDS Input/Output
21	DO1+/RIN1+	Channel 1 Noninverting BLVDS Input/Output
26	DE12	Driver Channels 1 and 2 Enable (Enable High). Drive DE12 high to enable driver channels 1 and 2. Internal pullup to $V_{\rm CC}$ .
29	RE12	Receiver Channels 1 and 2 Enable (Enable Low). Drive RE12 low to enable receiver channels 1 and 2. Internal pullup to VCC.
35	DIN1	Driver Channel 1 Input
36	RO1	Receiver Channel 1 Output
37	DIN2	Driver Channel 2 Input
38	RO2	Receiver Channel 2 Output
40	DIN3	Driver Channel 3 Input
41	RO3	Receiver Channel 3 Output
42	DIN4	Driver Channel 4 Input
43	RO4	Receiver Channel 4 Output
EP	EXPOSED PAD	Exposed Pad. Solder exposed pad to GND.

### **Detailed Description**

The MAX9158 is a four-channel, 200Mbps, 3.3V BLVDS transceiver in a 44-lead QFN package, ideal for driving heavily loaded multipoint buses, typically 16 to 20 cards plugged into a backplane. The MAX9158 receivers accept a differential input and have a fail-safe input circuit. The devices detect differential signals as low as 100mV and as high as VCC.

The MAX9158 driver outputs use a current-steering configuration to generate a 9.25mA to 17mA output current. This current-steering approach induces less ground bounce and no shoot-through current, enhancing noise margin and system speed performance. The outputs are short-circuit current limited.

The MAX9158 current-steering output requires a resistive load to terminate the signal and complete the transmission loop. Because the devices switch the direction of current flow and not voltage levels, the output voltage swing is determined by the value of the termination resistor multiplied by the output current. With a typical 14.75mA output current, the MAX9158 produces a 398mV output voltage when driving a bus terminated with two  $54\Omega$  resistors (14.75mA  $\times$  27 $\Omega$  = 398mV). Logic states are determined by the direction of current flow through the termination resistor.

#### Fail-Safe Receiver Inputs

The fail-safe feature of the MAX9158 sets the receiver output high when the receiver differential input is:

- Open
- Undriven and shorted
- · Undriven and terminated

Without a fail-safe circuit, when the input is undriven, noise at the input may switch the output and it may appear to the system that data is being received. Open or undriven terminated input conditions can occur when a cable is disconnected or cut, or when a driver is in high impedance. A shorted input can occur because of a cable failure.

When the input is driven with a differential signal with a common-mode voltage of 0.05V to 2.4V, the fail-safe circuit is not activated. If the input is open, undriven and shorted, or undriven and parallel terminated, an internal resistor in the fail-safe circuit pulls both inputs above  $V_{CC}$  - 0.3V, activating the fail-safe circuit and forcing the output high (Figure 1).

### **Effect of Capacitive Loading**

The characteristic impedance of a differential PC board trace is uniformly reduced when equal capacitive loads are attached at equal intervals (provided the transition time of the signal being driven on the trace is longer than the delay between loads). This kind of loading is typical of multipoint buses where cards are attached at 1 in or 0.8 in intervals along the length of a backplane.

The reduction in characteristic impedance is approximated by the following formula:

 $Z_{DIFF}$ -loaded =  $Z_{DIFF}$ -unloaded  $\times$  SQRT [Co / (Co + N  $\times$  C<sub>L</sub> / L)]

where:

ZDIFF-unloaded = unloaded differential characteristic impedance

Co = unloaded trace capacitance (pF/unit length)

 $C_L$  = value of each capacitive load (pF)

N = number of capacitive loads

L = trace length

For example, if Co = 2.5pF/in,  $C_L$  = 10pF, N = 18, L = 18in, and  $Z_{DIFF}$ -unloaded = 120 $\Omega$ , the loaded differential impedance is:

ZDIFF-loaded =  $120\Omega$  X SQRT [2.5pF / (2.5pF +  $18 \times 10$ pF / 18in)] ZDIFF-loaded =  $54\Omega$ 

In this example, capacitive loading reduces the characteristic impedance from  $120\Omega$  to  $54\Omega$ . The load seen by

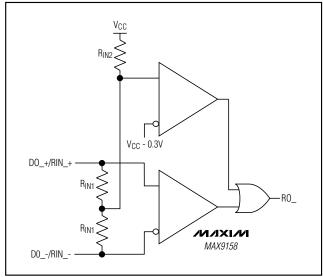


Figure 1. Internal Fail-Safe Circuit

a driver located on a card in the middle of the bus is  $27\Omega$  because the driver sees two  $54\Omega$  loads in parallel. A typical LVDS driver (rated for a  $100\Omega$  load) would not develop a large enough differential signal to be reliably detected by an LVDS receiver. The MAX9158 BLVDS drivers are designed and specified to drive a  $27\Omega$  load to differential voltage levels of 250mV to 460mV. A standard LVDS receiver is able to detect this level of differential signal. Short extensions off the bus, called stubs, contribute to capacitive loading. Keep stubs less than 1 in for a good balance between ease of component placement and good signal integrity.

The MAX9158 driver outputs are current-source drivers and drive larger differential signal levels into loads lighter than  $27\Omega$  and smaller levels into loads heavier than  $27\Omega$  (see  $Typical\ Operating\ Characteristics\ curves). To keep loading from reducing bus impedance below the rated <math display="inline">27\Omega$  load, PC board traces can be designed for higher unloaded characteristic impedance.

#### **Effect of Transition Times**

For transition times (measured from 0% to 100%) shorter than the delay between capacitive loads, the loads are seen as low-impedance discontinuities from which the driven signal is reflected. Reflections add and subtract from the signal being driven, causing jitter and decreased noise margin. The MAX9158 output drivers are designed for a minimum transition time of 1ns (rated 0.6ns from 20% to 80%, or 1ns from 0% to 100%) to reduce reflections while being fast enough for high-speed backplane data transmission.

#### **Power-On Reset**

The power-on reset voltage of the MAX9158 is typically 2.25V. When the supply falls below this voltage, the devices are disabled and the receiver inputs/driver outputs are in high impedance. The power-on reset ensures glitch-free power-up and power-down, allowing hot swapping of cards in a multicard bus system without disrupting communications.

#### **Operating Modes**

The MAX9158 features driver/receiver enable inputs that select the bus I/O function (Table 1). Tables 2 and 3 show the driver and receiver operating modes.

# Input Internal Pullup/Pulldown Resistors

The MAX9158 includes pullup or pulldown resistors (300k $\Omega$ ) to ensure that unconnected inputs are defined (Table 4).

### **Applications Information**

### **Supply Bypassing**

Bypass each supply pin with high-frequency surface-mount ceramic  $0.1\mu F$  and 1nF capacitors in parallel as close to the device as possible, with the smaller value capacitor closest to the device.

#### **Termination**

In the example given in the Effect of Capacitive Loading section, the loaded differential impedance of a bus is reduced to  $54\Omega$ . Since the bus can be driven from any card position, the bus must be terminated at each end. A parallel termination of  $54\Omega$  at each end of the bus placed across the traces that make up the differential pair provides a proper termination. The total load seen by the driver is  $27\Omega$ . The MAX9158 drives higher differential signal levels into lighter loads. (See the Differential Output Voltage vs. Output Load graph in the Typical Operating Characteristics section.) A multidrop bus with the driver at one end and receivers connected at reqular intervals along the bus has a lowered impedance due to capacitive loading. Assuming a  $54\Omega$  impedance, the multidrop bus can be terminated with a single, parallel-connected  $54\Omega$  resistor at the far end from the driver. Only a single resistor is required because the driver sees one  $54\Omega$  differential trace. The signal swing is larger with a  $54\Omega$  load. In general, parallel terminate each end of the bus with a resistor matching the differential impedance of the bus (taking into account any reduced impedance due to loading).

Table 1. I/O Enable Functional Table

MODE SELECTED	DE_	RE_
Driver Mode	Н	Н
Receiver Mode	L	L
High-Impedance Mode	L	Н
Loopback Mode	Н	L

**Table 2. Driver Mode** 

INPUTS		OUTPUTS		
DE_	DIN_	DO_+/RIN_+	DO/RIN	
Н	L	L	Н	
Н	Н	Н	L	
L	Χ	Z	Z	

#### **Table 3. Receiver Mode**

	INPUTS	
RE_	$V_{ID} = (V_{DO\_+}/R_{IN\_+}) - (V_{DO\}/R_{IN\})$	RO_
L	V <sub>ID</sub> < -100mV	L
L	V <sub>ID</sub> > 100mV	Н
L	Fail-safe operation guaranteed when DO_+/RIN_+ and DO/RIN are open, undriven and shorted, or undriven and parallel terminated	Н
Н	Х	Z

# Table 4. Input Internal Pullup/Pulldown Resistors

PIN	INTERNAL RESISTOR
DE12	Pullup to V <sub>CC</sub>
DE34	Pullup to V <sub>CC</sub>
RE12	Pullup to V <sub>CC</sub>
RE34	Pullup to V <sub>CC</sub>
DIN_	None (floating)

### Traces, Cables, and Connectors

The characteristics of input and output connections affect the performance of the MAX9158. Use controlled-impedance traces, cables, and connectors with matched characteristic impedance.

Ensure that noise couples as common mode by running the traces of a differential pair close together. Reduce within-pair skew by matching the electrical length of the traces of a differential pair. Excessive skew can result in a degradation of magnetic field cancellation. Maintain the distance between traces of a differential pair to avoid discontinuities in differential impedance. Minimize the number of vias to further prevent impedance discontinuities.

Avoid the use of unbalanced cables, such as ribbon cable. Balanced cables, such as twisted pair, offer superior signal quality and tend to generate less EMI due to canceling effects. Balanced cables tend to pick up noise as common mode, which is rejected by the receiver.

#### **Board Layout**

A four-layer PC board that provides separate power, ground, input, and output signals is recommended. Keep the LVTTL/LVCMOS and BLVDS signals separated to prevent coupling.

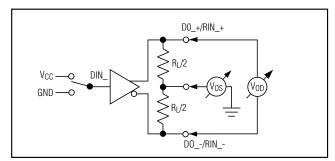


Figure 2. Driver VoD and Vos Test Circuit

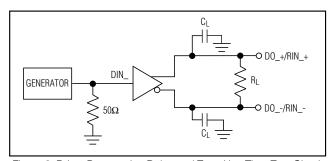


Figure 3. Driver Propagation Delay and Transition Time Test Circuit

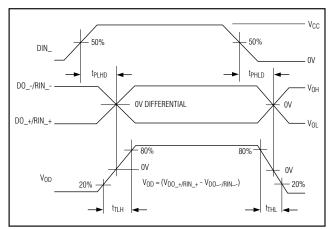


Figure 4. Driver Propagation Delay and Transition Time Waveforms

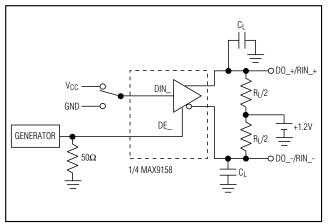


Figure 5. Driver High-Impedance Delay Test Circuit

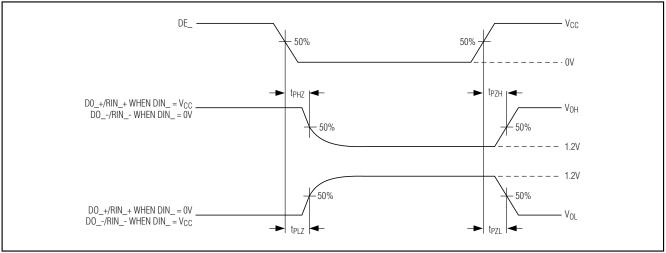


Figure 6. Driver High-Impedance Delay Waveform

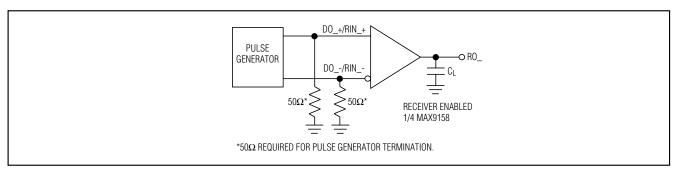


Figure 7. Receiver Transition Time and Propagation Delay Test Circuit

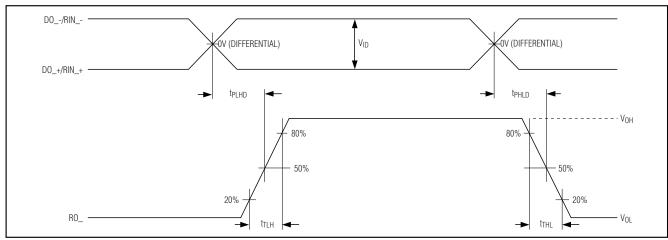


Figure 8. Receiver Transition Time and Propagation Delay Timing Diagram

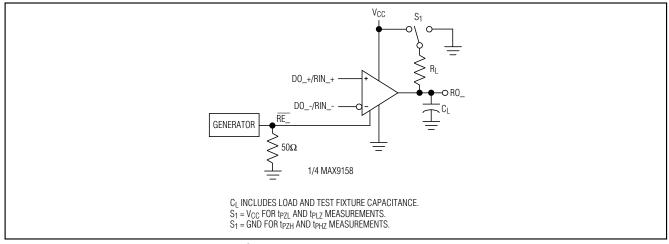


Figure 9. Receiver High-Impedance Delay Test Circuit

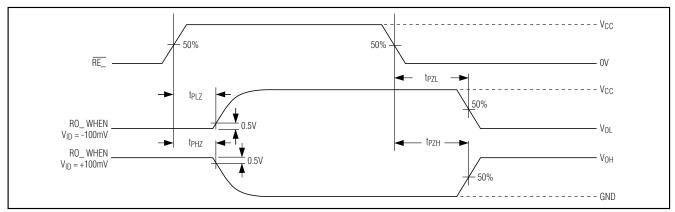


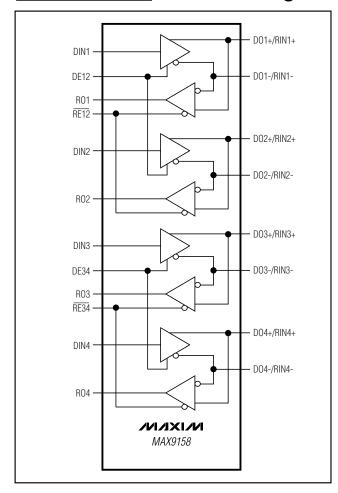
Figure 10. Receiver High-Impedance Waveforms

### **Functional Diagram**

# Chip Information

TRANSISTOR COUNT: 1796

PROCESS: CMOS

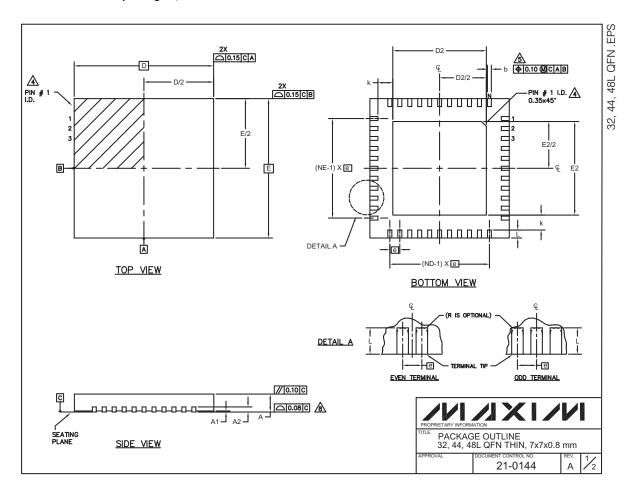


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# **Quad Bus LVDS Transceiver in 44 QFN**

### **Package Information**

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)



### Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)

COMMON DIMENSIONS												
PKG	32L 7x7			44L 7x7			48L 7x7			CUSTOM PKG. (T4877-1) 48L 7x7		
FNG												
SYMBOL	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
Α	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80
A1	0	0.02	0.05	0	0.02	0.05	0	0.02	0.05	0	0.02	0.05
A2	0.20 REF.			0.20 REF.			0.20 REF.			0.20 REF.		
b	0.25	0.30	0.35	0.20	0.25	0.30	0.20	0.25	0.30	0.20	0.25	0.30
D	6.90	7.00	7.10	6.90	7.00	7.10	6.90	7.00	7.10	6.90	7.00	7.10
E	6.90	7.00	7.10	6.90	7.00	7.10	6.90	7.00	7.10	6.90	7.00	7.10
8	0.65 BSC.			0.50 BSC.			0.50 BSC.			0.50 BSC.		
k	0.25	-		0.25	-	-	0.25	-	-	0.25	•	-
L	0.45	0.55	0.65	0.45	0.55	0.65	0.30	0.40	0.50	0.45	0.55	0.65
N	32			44			48			44		
ND	8			11			12			10		
NE	8		11			12			12			

EXPOSED PAD VARIATIONS										
PKG. CODES	DEPOPULATED		D2		E2			JEDEC MO220		
	LEADS	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.			
T3277-1	-	4.55	4.70	4.85	4.55	4.70	4.85	-		
T4477-1	-	4.55	4.70	4.85	4.55	4.70	4.85	WKKD-1		
T4877-1**	13, 24, 37, 48	4.20	4.30	4.40	4.20	4.30	4.40			
T4877-2	-	5.45	5.60	5.75	5.45	5.60	5.75	WKKD-2		

\*\* NOTE: T4877-1 IS A CUSTOM 48L PKG. WITH 4 LEADS DEPOPULATED TOTAL NUMBER OF LEADS ARE 44.

#### NOTES:

- 1. DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.
- 3. N IS THE TOTAL NUMBER OF TERMINALS.
- THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION SHALL CONFORM TO JESD 95-1 SPP-012. DETAILS OF TERMINAL #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE TERMINAL #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE.
- DIMENSION & APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.25 mm AND 0.30 mm FROM TERMINAL TIP.
- AD AND NE REFER TO THE NUMBER OF TERMINALS ON EACH D AND E SIDE RESPECTIVELY.
- 7. DEPOPULATION IS POSSIBLE IN A SYMMETRICAL FASHION.
- COPLANARITY APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.
- 9. DRAWING CONFORMS TO JEDEC MO220 REVISION C.
- 10. WARPAGE SHALL NOT EXCEED 0.10 mm.



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